Specification

Drawing No.	UKY1C-H1-16B35-00[43] 1/10
Issued Date.	Nov.25,2016

TO: Microchip Corporation

Note: In case of specification change, KYOCERA Part Number also will be changed.

Product Name	Quartz Crystal
Product Model	CX3225CA
Frequency	16000kHz
Customer Part Number	-
Customer Specification Number	-
KYOCERA Part Number	CX3225CA16000D0KPSC1
Remarks RoHS Compliant, MSL 1 AEC-Q200 Compliant	

Customer Acceptance

Accept Signature	Approved Date	
	Department	
	Person in charge	

Seller

KYOCERA Crystal Device Corporation

(Sales Division)

6 Takeda Tobadono-cho, Fushimi-ku, Kyoto

612-8501 Japan

TEL. No. 075-604-3500 FAX. No. 075-604-3501

Manufacturer

KYOCERA Crystal Device Corporation

Crystal Units Division

5850, Higashine-Koh, Higashine-Shi, Yamagata

999-3701 Japan

TEL. No. 0237-43-5611 FAX. No. 0237-43-5615

Design Department	Quality Assurance	Approved by	Examination by	Issued by
KYOCERA Crystal Device Corporation Crystal Units Engineering Section Crystal Units Division	W.Muraoka	H. Shoji	A.lto	M.Hashimoto

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Revision History

Rev.No.	Description of revise	Date	Approved by	Examination by	Issued by
1	First Edition	Nov.25,2016	H. Shoji	A.Ito	M.Hashimoto

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1. APPLICATION

This specification sheet is applied to quartz crystal "CX3225CA16000D0KPSC1"

2. KYOCERA PART NUMBER

CX3225CA16000D0KPSC1

3. RATINGS

Items	SYMB.	Rating	Unit	Remarks
Operating Temperature	Topr	-40 to +85	°C	
Storage Temperature Range	Tstg	-40 to +150	°C	

4. CHARACTERISTICS ELECTRICAL CHARACTERISTICS

Items		Electrical Specification			Test Condition	Remarks	
	SYMB.	Min.	Тур.	Max.	Unit		
Mode of Vibration			Fundamental				
Nominal	F0		16		MHz		
Frequency							
Nominal	T _{NOM}		+25		°C		
Temperature							
Load Capacitance	CL		8.0		pF		
Frequency	df/F	-30.0		+30.0		+25±3°C	
Tolerance							
Frequency	df/F	-50.0		+50.0		-40 to +85°C	
Temperature					PPM		
Characteristics							
Frequency Aging		-5.0		+5.0		1 st year	+25±3°C
Rate							
Equivalent Series	ESR			100	Ω		
Resistance							
Drive Level	Pd	0.01		200	μW		
Insulation	IR	500			ΜΩ	100V(DC)	
Resistance							

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5. Measurement Condition

5.1 Frequency measurement

Measuring instrument : IEC PI-Network Test Fixture

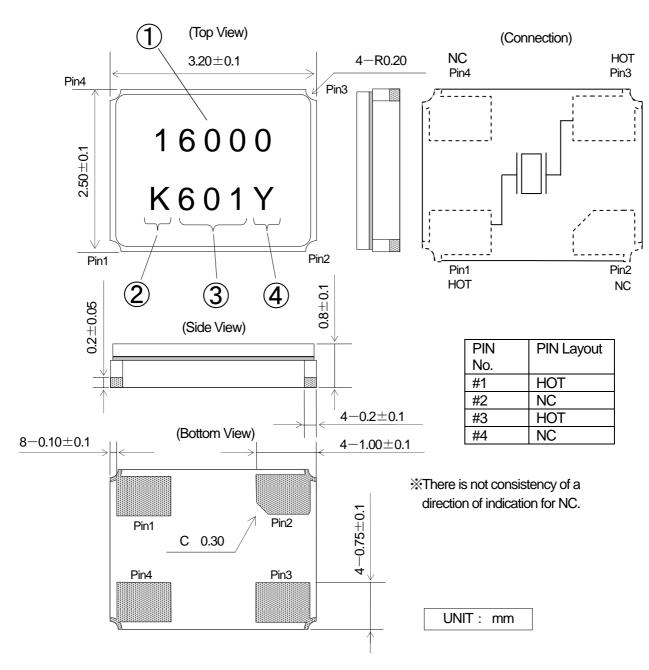
Load Capacitance : 8.0pF Drive Level : 10µW

5.2 Equivalent series resistance (ESR) measurement

Measuring instrument : IEC PI-Network Test Fixture

Load Capacitance : Series
Drive Level : 10µW

6. APPEARANCES, PHYSICAL DIMENSION OUTLINE DIMENSION (not to scale)



MARKING

1 Nominal Frequency Move the number of maximum indication beams of the

frequency to five digits, and omit less than kHz.

2 Identification

3 Date Code Year…LAST 1 DIGIT of YEAR AND WEEK

(Ex) Jan. 1, 2016 \rightarrow 601

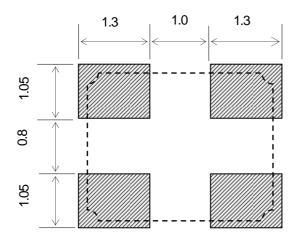
4 Manufacturing Location Y···Japan(Yamagata)

 $T{\cdots} Thail and \\$

%The font of marking is reference.

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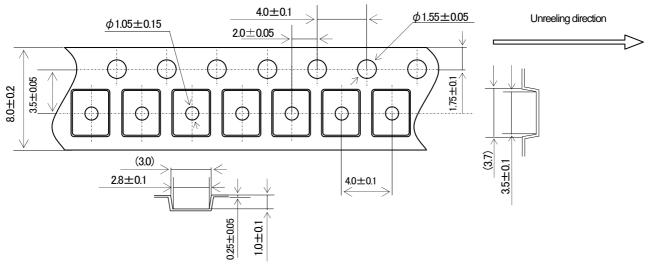
7. RECOMMENDED LAND PATTERN (not to scale)



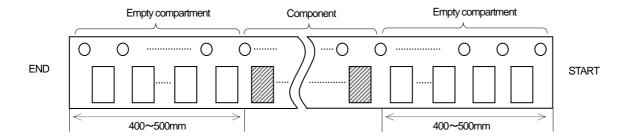
UNIT: mm

8.TAPING & REEL

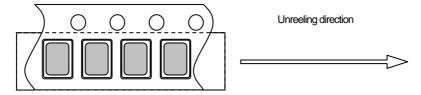
8-1.Dimensions



8-2.Leader and trailer tape

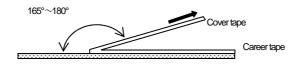


8-3. Direction (The direction shall be seen from the top cover tape side)

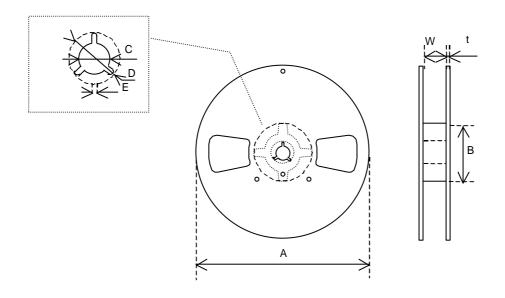


8-4.Specification

- 1. Material of the carrier tape is either polystyrene or A-PET (ESD).
- 2. Material of the cover tape is polyester (ESD).
- 3. The seal tape shall not cover the sprocket holes and not protrude from the carrier tape.
- 4. Tensile strength of carrier tape: 10N or more.
- 5. The R of the comer of each cavity is 0.2RMAX.
- 6. The alignment between centers of the cavity and sprocket hole shall be 0.05mm or less.
- 7. Peeling force of cover tape: 0.1 to 1.0N.
- 8. The component will fall out naturally when cover tape is removed and set upside down.
- 9. The marking on parts is not fixed its direction, its electrical characteristic is equal.



8-5.Reel specifications



(Nonconductor type Reel)

Ф180 Reel (3000pcs max.)

	<u>'</u>			
	A	В	С	D
Dimension	φ180 +0/-1.5	φ60 +1/-0	φ13±0.2	φ21±0.8
Symbol	E	W	t	
Dimension	2.0±0.5	9±1	2.0±0.5	

(Unit: mm)

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9.Enviromental requirements

(Reference: AEC-Q200 Rev. D. The solder used by examination is hereafter set to Sn-3Ag-0.5Cu.) After following test, Frequency applies to each item and CI, $\pm 20\%$ or 5Ω of large value.

No	Stress	Reference	Additional Requirements
9.1	High Temperature Exposure	MIL-STD-202	1000 hrs. at rated operating temperature (e.g. 85°C
	(Storage)	Method 108	part can be stored for 1000 hrs at 85°C. Same applies
			for 125°C). Unpowered.
			Measurement at 24±4 hours after test conclusion.
9.2	Temperature Cycling	JESD22	1000 cycles (-40°C to 125°C) Note: If 85°C part the
		Method JA-104	1000 cycles will be at that temperature rating.
			Measurement at 24±4 hours after test conclusion.
			30min maximum dwell time at each temperature
			extreme. 1 min. maximum transition time.
9.3	Biased Humidity	MIL-STD- 202	1000 hours 85°C/85%RH. Rated VDD applied with 1
		Method 103	MW and inverter in parallel, 2X crystal CL capacitors
			between each crystal leg and GND.
			Measurement at 24±4 hours after test conclusion.
9.4	Operational Life	MIL-STD- 202	Note: 1000 hrs @ 125°C. If 85°C part will be tested at
		Method 108	that temperature. Rated VDD applied with 1 MW and
			inverter in parallel, 2X crystal CL capacitors between
			each crystal leg and GND.
			Measurement at 24±4 hours after test conclusion.
9.5	Terminal Strength (Leaded)	MIL-STD- 202	Test leaded device lead integrity only. Conditions: A
		Method 211	(227 g), C (227 g).
9.6	Resistance to Solvents	MIL-STD- 202	Note: Also aqueous wash chemical - OKEM clean or
		Method 215	equivalent. Do not use banned solvents.
9.7	Mechanical Shock	MIL-STD-202	Figure 1 of Method 213. Condition C
	l New York	Method 213	
9.8	Vibration	MIL-STD-202	5g's for 20 minutes 12 cycles each of 3 orientations.
		Method 204	Note: Use 8"X5" PCB .031" thick with 7 secure points
			on one 8" side and 2 secure points on corners of
			opposite sides. Parts mounted within 2" from any secure point. Test from 10-2000 Hz.
9.9	Resistance to	MIL-STD-202	Condition B No pre-heat of samples. Note: Single
9.9	Soldering Heat	Method 210	Wave solder - Procedure 1 with solder within 1.5 mm
	Soldering Heat	IVIELLIOU Z TO	of device body for Leaded. Procedure 1 except 230°C
			and immerse only to level to cover terminals for SMD.
9.10	Solder ability	J-STD-002	For both Leaded & SMD. Electrical Test not required.
5.10	Coldor dollity	0.010-002	Magnification 50 X. Conditions:
			Leaded: Method A @ 235°C, category 3.
			SMD: a) Method B, 4 hrs @ 155°C dry heat @ 235°C
			b) Method B @ 215°C category 3.
			c) Method D category 3 @ 260°C.
9.11	Flammability	UL-94	V-0 or V-1 Acceptable
9.12	Board Flex	AEC Q200-005	60 sec minimum holding time.
9.13	Terminal Strength(SMD)	AEC Q200-006	-
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10. Cautions for use

(1) Soldering upon mounting

There is a possibility to influence product characteristics when Solder paste or conductive glue comes in contact with product lid or surface.

(2) When using mounting machine

Please minimize the shock when using mounting machine to avoid any excess stress to the product.

(3) Conformity of a circuit

We strongly recommend to make sure that Negative resistance (Gain) of IC is designed to be 10 times the ESR (Equivalent Series Resistance) of crystal unit.

(4) After making the Quartz Crystal mount on a printed circuit board, if it is required to divide the printed circuit board into another one, use it with attentive confirmation so that a warp cased by this dividing might not affect any damage. When designing a printed circuit board as well as handling the mounting As much as possible. The quartz crystal shall be passed through the reflow furnace. Then it shall be subjected to standard atmospheric conditions, after which cleaning shall be made.

11. Storage conditions

Please store product in below conditions, and use within 6 months.

Temperature +18 to +30 $^{\circ}$ C, and Humidity of 20 to 70 $^{\circ}$ 6 in the packaging condition.

12. Manufacturing location

Kyocera Crystal Device Corporation / Japan(Yamagata)

Kyocera Crystal Device (Thailand) Co., Ltd / Thailand(Lamphun)

13. Quality Assurance

To be guaranteed by Kyocera Crystal Device Quality Assurance Division

14. Quality guarantee

In case when Kyocera Crystal Device Corporation rooted failure occurred within 1year after its delivery, substitute product will be arranged based on discussion. Quality guarantee of product after 1year of its delivery is waivered.

15. Others

In case of any questions or opinions regarding the Specification, please have it in written manner within 45 days after issued date.